Power MOSFET

100 V, 20 m Ω , 41 A, Single N-Channel

Features

- Low R_{DS(on)} to Minimize Conduction Losses
- High Current Capability
- Avalanche Energy Specified
- AEC-Q101 Qualified
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	100	V
Gate-to-Source Voltage	Gate-to-Source Voltage			±20	V
Continuous Drain Cur-		T _C = 25°C	I _D	41	Α
rent R _{θJC} (Note 1)	Steady	T _C = 100°C		29	
Power Dissipation R _{θJC}	State	T _C = 25°C	P_{D}	90	W
(Note 1)		T _C = 100°C		45	
Continuous Drain Cur-		T _A = 25°C	I _D	8.5	Α
rent R _{θJA} (Notes 1 & 2)	Steady State	T _A = 100°C		6.0	
Power Dissipation R _{θJA}		T _A = 25°C	P_{D}	3.9	W
(Notes 1 & 2)		T _A = 100°C		1.9	
Pulsed Drain Current	T _A = 25°	$T_A = 25^{\circ}C, t_p = 10 \mu s$		238	Α
Current Limited by Package (Note 3)	T _A	= 25°C	I _{Dmaxpkg}	60	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to 175	°C
Source Current (Body Diode)			IS	41	Α
Single Pulse Drain-to-Source Avalanche Energy (T _J = 25°C, V _{GS} = 10 V, $I_{L(pk)}$ = 40 A, L = 0.1 mH, R _G = 25 Ω)			E _{AS}	80	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Drain)	$R_{\theta JC}$	1.7	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	39	

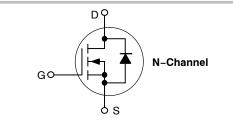
- 1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Continuous DC current rating. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



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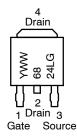
V _{(BR)DSS}	R _{DS(on)}	I _D	
100 V	20 mΩ @ 10 V	41 A	
	23 mΩ @ 4.5 V	417	





MARKING DIAGRAMS & PIN ASSIGNMENT

STYLE 2



= Year WW = Work Week 6824L = Device Code = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
NVD6824NLT4G	DPAK (Pb-Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS						•	•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		100			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				92		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 100 V	$T_J = 25^{\circ}C$ $T_J = 125^{\circ}C$			1.0	μΑ
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS}				± 100	nA
ON CHARACTERISTICS (Note 4)	GOO						1
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D	= 250 μΑ	1.5		2.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J	vGs - vDs, iD = 230 μA			-6.5		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _E) = 20 A		16.5	20	mΩ
		V _{GS} = 4.5 V, I _I	_O = 20 A		18.5	23	1
Forward Transconductance	gFS	V _{DS} = 15 V, I _E) = 20 A		18		S
CHARGES, CAPACITANCES AND GA	TE RESISTANCE	S			· L		
Input Capacitance	C _{iss}				3468		pF
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V, f} = 0 \text{ V}$ $V_{DS} = 25 \text{ V}$			187		1
Reverse Transfer Capacitance	C _{rss}	VDS = 23) V		133		1
Total Gate Charge	Q _{G(TOT)}				34		nC
	-				66		
Threshold Gate Charge	Q _{G(TH)}				3.5		1
Gate-to-Source Charge	Q _{GS}	$V_{GS} = 10 \text{ V}, V_{D}$ $I_{D} = 20$			9.0		1
Gate-to-Drain Charge	Q_{GD}	ID - 20	^		18		1
SWITCHING CHARACTERISTICS (Not	e 5)					1	
Turn-On Delay Time	t _{d(on)}				15		ns
Rise Time	t _r	V_{GS} = 10 V, V_{D}	n = 80 V.		55		1
Turn-Off Delay Time	t _{d(off)}	$I_D = 20 \text{ A}, R_G$	= 2.5 Ω		31		1
Fall Time	t _f	1			42		1
DRAIN-SOURCE DIODE CHARACTEI	RISTICS					1	1
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V, I _S = 20 A	T _J = 25°C		0.84	1.2	V
			T _J = 125°C		0.71	ļ	
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dls/dt = 100 A/μs, l _S = 20 A			38	ļ	ns
Charge Time	ta				28		1
Discharge Time	tb				10		
Reverse Recovery Charge	Q_{RR}				59		nC

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

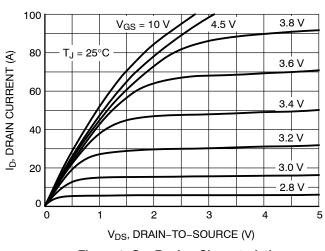


Figure 1. On-Region Characteristics

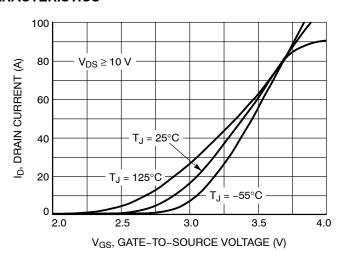


Figure 2. Transfer Characteristics

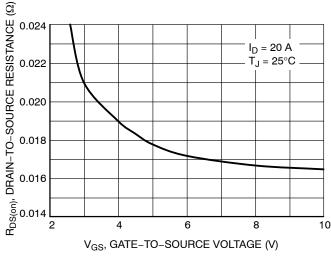


Figure 3. On-Resistance vs. Gate Voltage

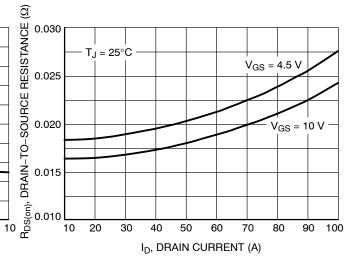


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

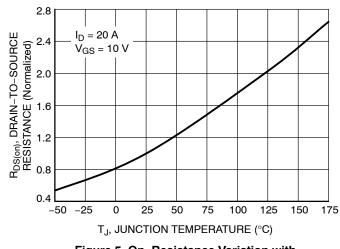


Figure 5. On–Resistance Variation with Temperature

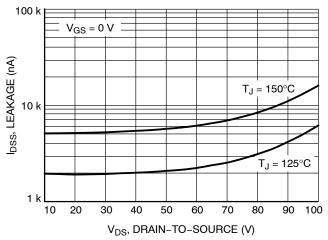
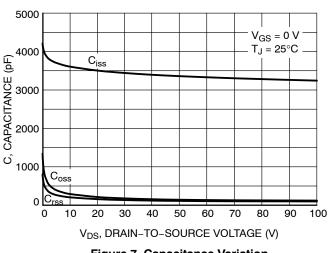


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

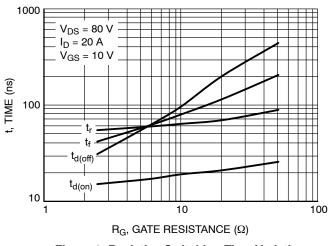


V_{GS}, GATE-TO-SOURCE VOLTAGE (V) 8 6 Qgs. Qgd $V_{DS} = 80 \text{ V}$ $I_{D} = 20 \text{ A}$ $T_J = 25^{\circ}C$ 10 20 30 40 50 60 70 Q_G, TOTAL GATE CHARGE (nC)

QT

Figure 7. Capacitance Variation

Figure 8. Gate-to-Source Voltage vs. Total Charge



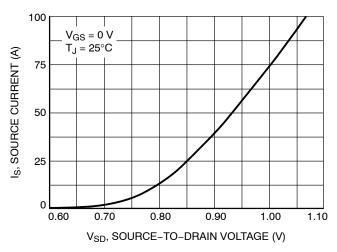


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Voltage vs. Current

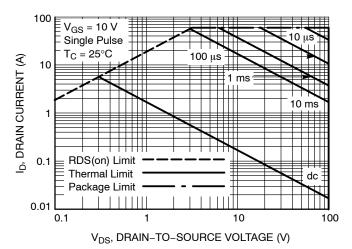


Figure 11. Maximum Rated Forward Biased **Safe Operating Area**

TYPICAL CHARACTERISTICS

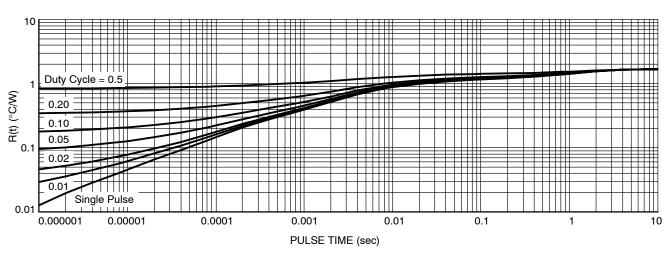
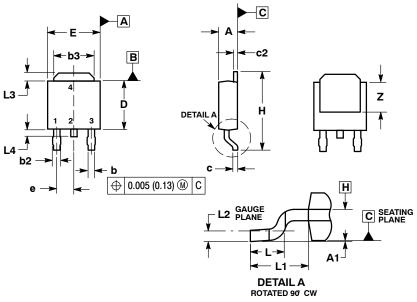


Figure 12. Thermal Response

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C ISSUE D



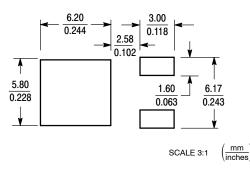
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES. 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
- MENSIONS DS, LS BITO Z.

 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM PI ANF H

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
Е	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29 BSC		
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108 REF		2.74	REF	
L2	0.020	BSC	0.51	BSC	
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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> Sales:

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Customer Service :

Email service@ameya360.com

Partnership :

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